Inventor:

Sujit Sharan et al.

Title:

Methods of Forming Silicon Dioxide Layers, and Methods of

Forming Trench Isolation Regions

Assignee:

Micron Technology, Inc.

Docket No.:

MI22-1421

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a continuation application of co-pending application Serial No. 09/497,080, filed February 2, 2000. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 30 May 2004

May 2004 Attorney:

James E. Lake

Reg. No. 44,854

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	AP	Gross, M., "Silicon Dioxide Trench Filling Process in a Radio-Frequency Hollow Cathode Reactor", J. Vac. Sci. Technol. B11(2), Mar./Apr. 1993, No. 2, pp. 242-248.								
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Sheet 2 of 3 ATTY. DOCKET NO. Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PRIORITY SERIAL NO. 09/497,080 PATENT AND TRADEMARK OFFICE MI22-1421 LIST OF ART CITED BY APPLICANT APPLICANT Sujit Sharan et al. (Use several sheets if necessary) PRIORITY FILING DATE February 2, 2000 PRIORITY GROUP U.S. PATENT DOCUMENTS *Examiner Document Date Name Subclass Filing Date Initial Number If Appropriate 6,174,785 6/1998 AA Parekh et al AB 6,165,854 5/1998 Wu 5,447,884 6/1994 AC Fahey et al ΑD 5,726,090 5/1997 Jang et al ΑE 5,660,895 4/1996 Lee et al AF 6,194,038 3/1998 Rossman AG 6,217,721 3/2001 Xu et al AΗ 6,013,584 1/2000 M'Saad ΑI 6,153,509 11/2000 Wantanbe 5,531,834 ΑJ 7/1996 Ishizuka et al ΑK 5,726,097 3/1998 Yanagida FOREIGN PATENT DOCUMENTS Date Class Subclass Translation Country Number Yes No 07-76777 03/1995 Japan 11-154673 06/1999 AM Japan AN ΑO OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) ΑP AO AR AS

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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